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(54) **Title:** ELECTRONIC DEVICE MANUFACTURING AQUEOUS SOLUTION, METHOD FOR PRODUCING RESIST PATTERN, AND METHOD FOR MANUFACTURING DEVICE

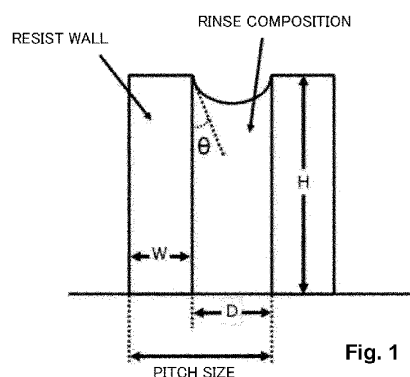


Fig. 1

(57) **Abstract:** [Problem] An object of the present invention is to provide an electronic device manufacturing aqueous solution, with which defects can be suppressed. [Means of Solution] An electronic device manufacturing aqueous solution including: an acid (A); a surfactant (B); and a solvent (C); wherein the acid (A) has a pKa (H₂O) of 3.0 or less, and a number of carbon atoms contained in the acid (A) is 0 to 8 in one molecule; the surfactant (B) is substantially free from ethylene oxide repeating units and propylene oxide repeating units; and the solvent (C) comprises water (C-1). The electronic device manufacturing aqueous solution is a high-performance material that can be used in the nanotechnology process of semiconductor device manufacturing, for example, in the manufacturing process of semiconductor devices that control liquid crystal, quantum dot, or OLED displays formed on a substrate.